

008027 94123650

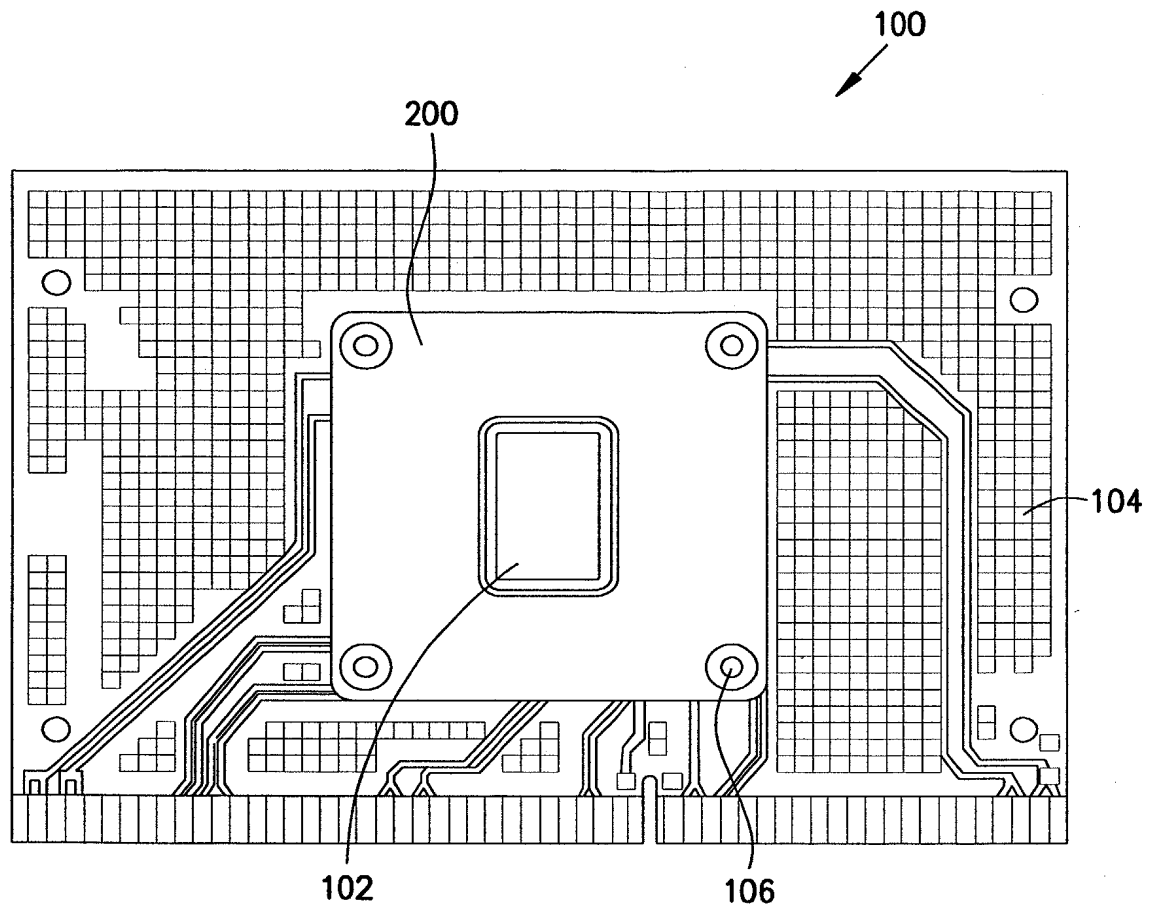


FIG. 1

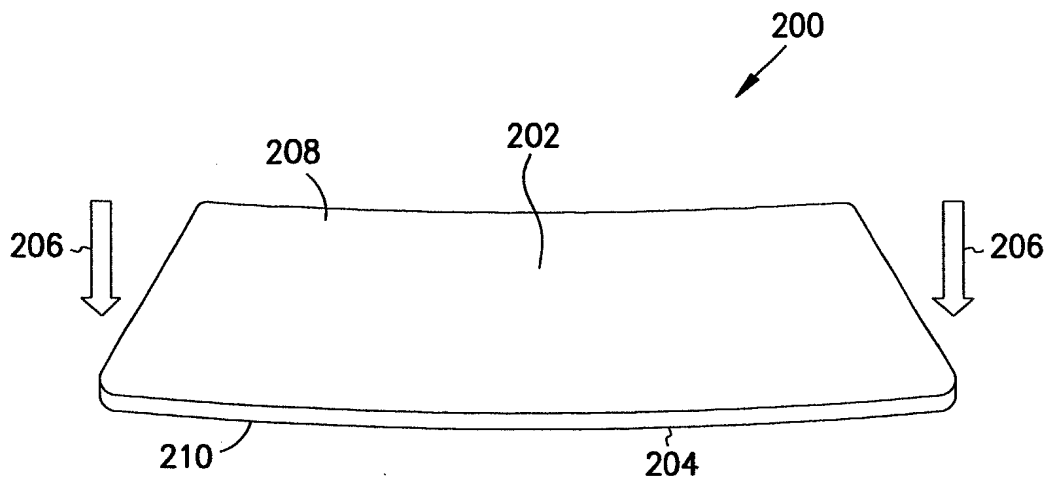


FIG. 2

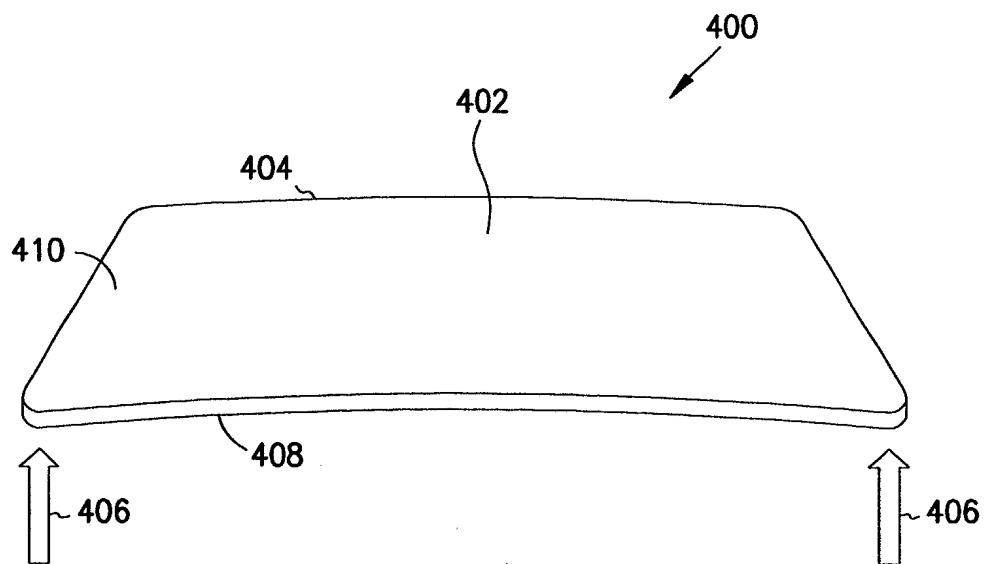


FIG. 4

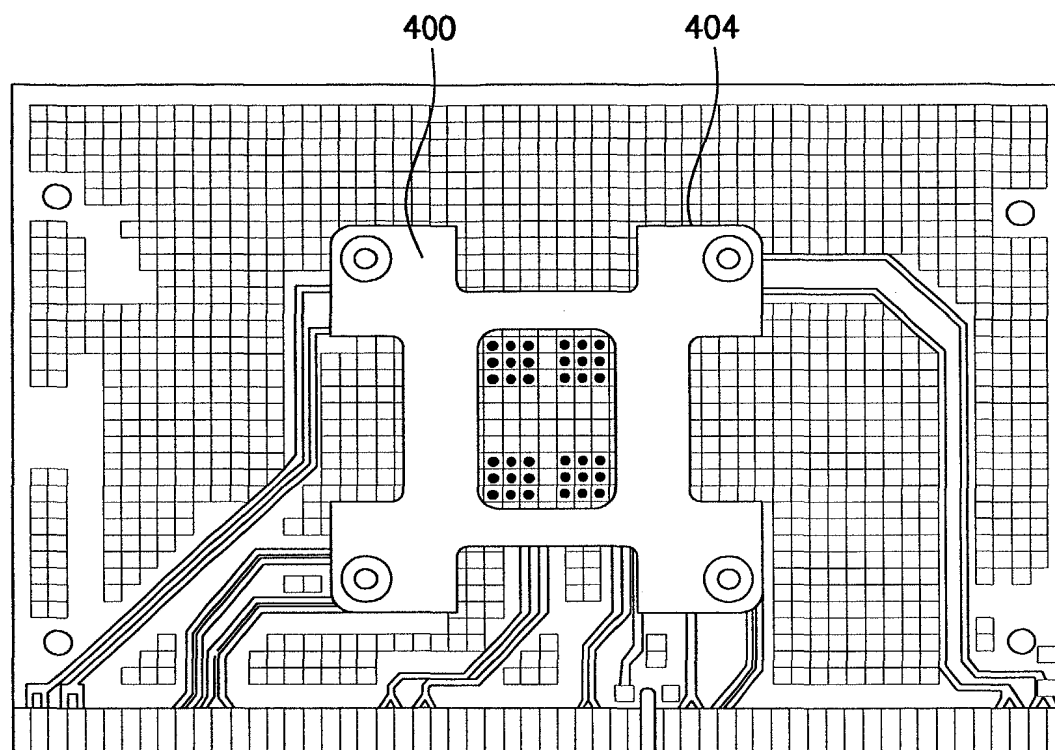
[illegible]

FIG. 3

This diagram shows an exploded perspective view of a multi-layered assembly, designated by the numeral 6. The assembly consists of several components aligned vertically:

- Top Layer (200):** A square plate with a central square opening. It is secured by four screws (106) around its perimeter and a central screw (106) passing through the opening.
- Ring (500):** A square ring-shaped component positioned below the top layer.
- Plate (102):** A square plate with a central rectangular protrusion, positioned below the ring.
- Plate (504):** A square plate positioned below the plate 102.
- Main Body (104):** A large, thin rectangular plate forming the base of the assembly.
- Bottom Layer (400):** A square plate with a central square opening, positioned below the main body. It is secured by four screws (106) around its perimeter and a central screw (106) passing through the opening.

Vertical dashed lines indicate the alignment of the components. The numeral 6 is shown with arrows pointing to the overall assembly.

FIG. 5

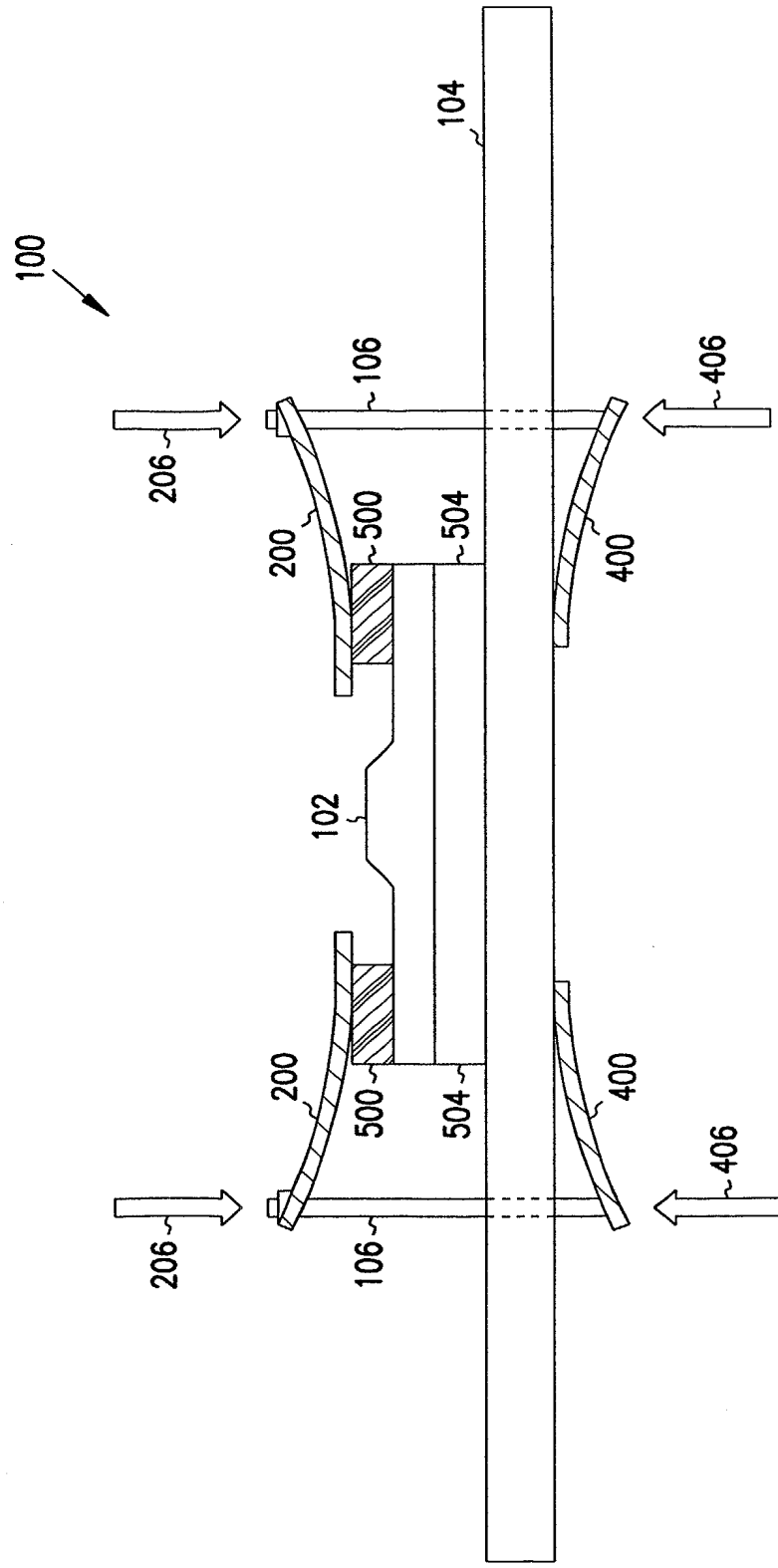


FIG. 6

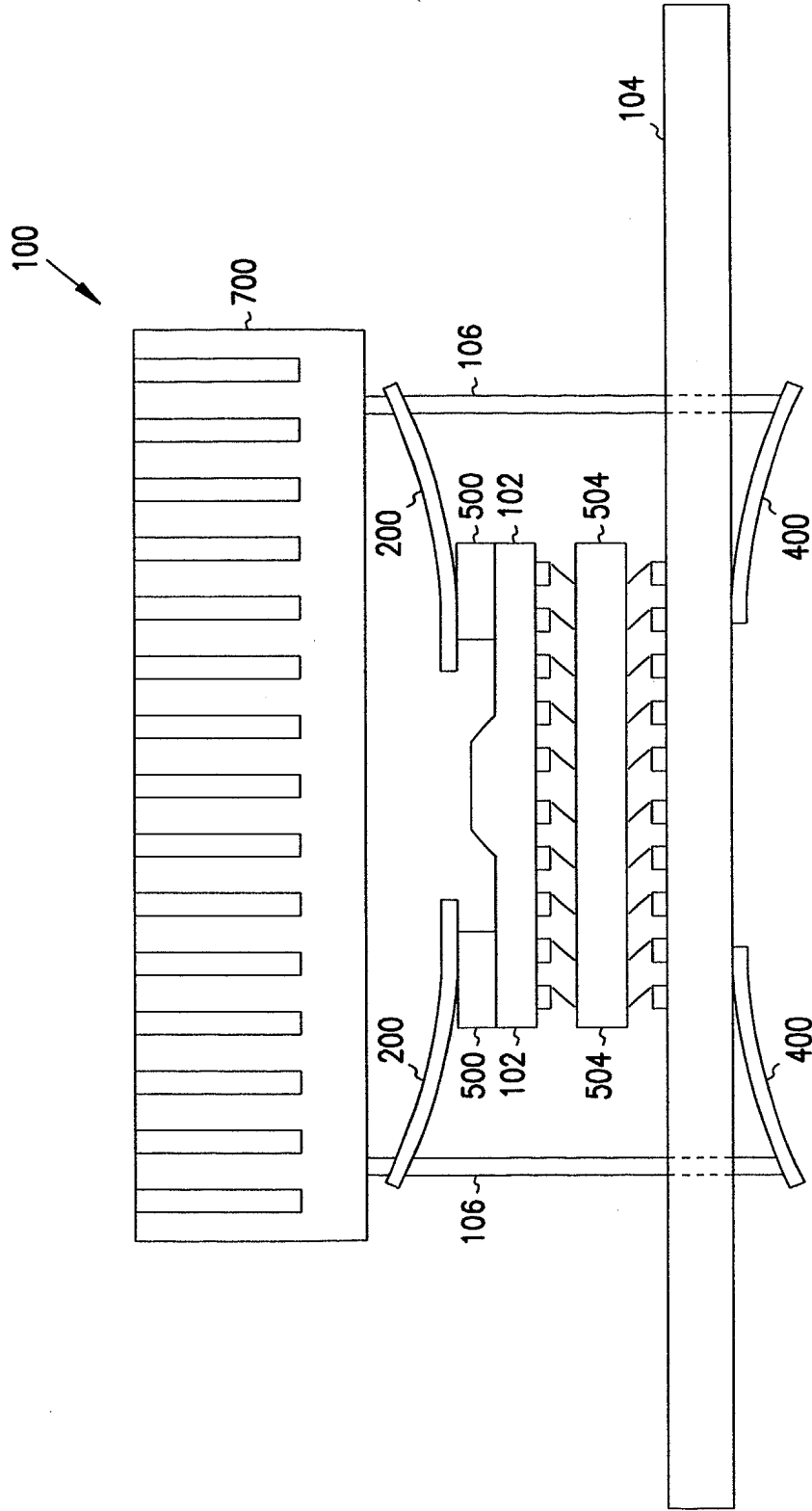


FIG. 7

000001 346660

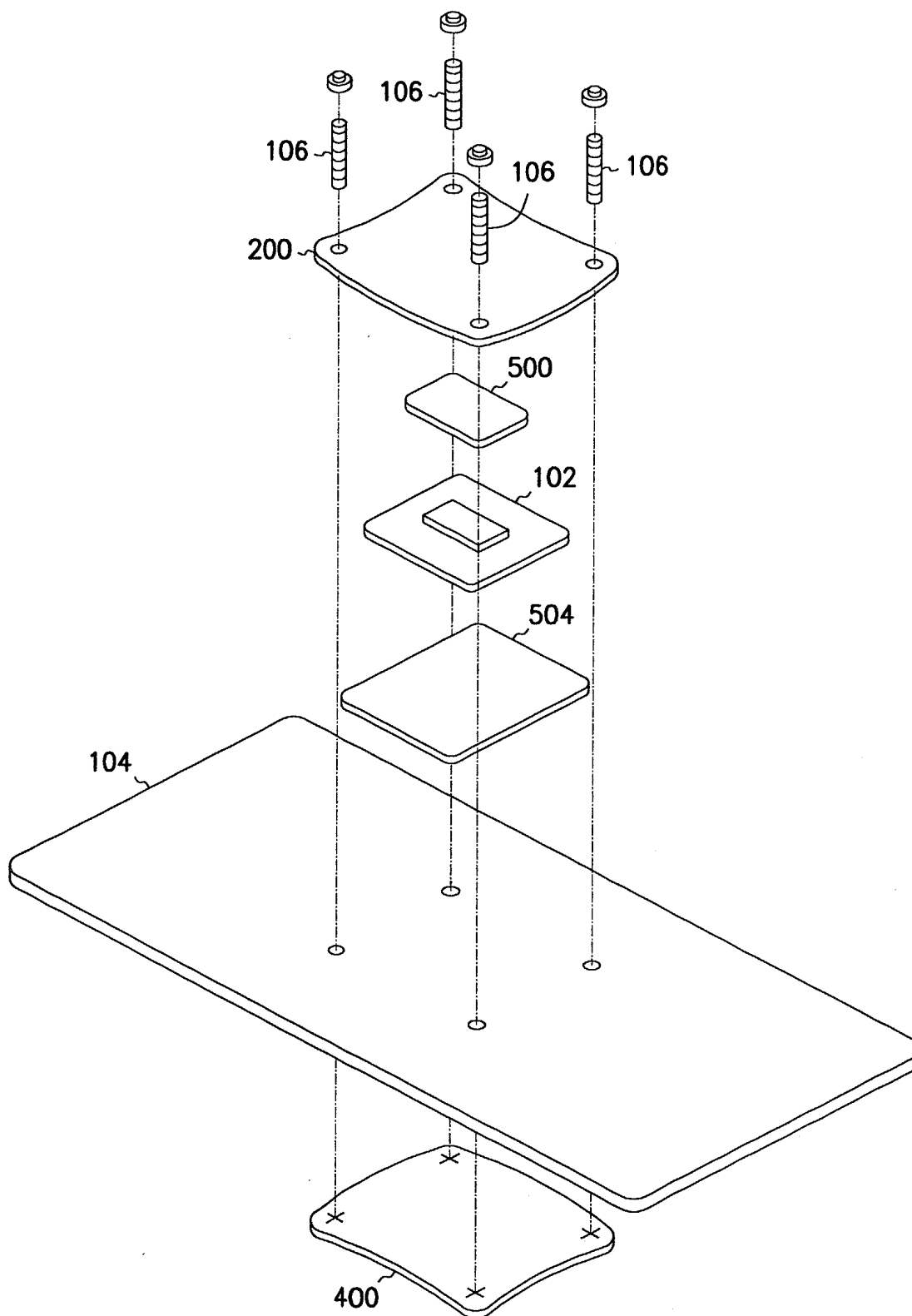


FIG. 8

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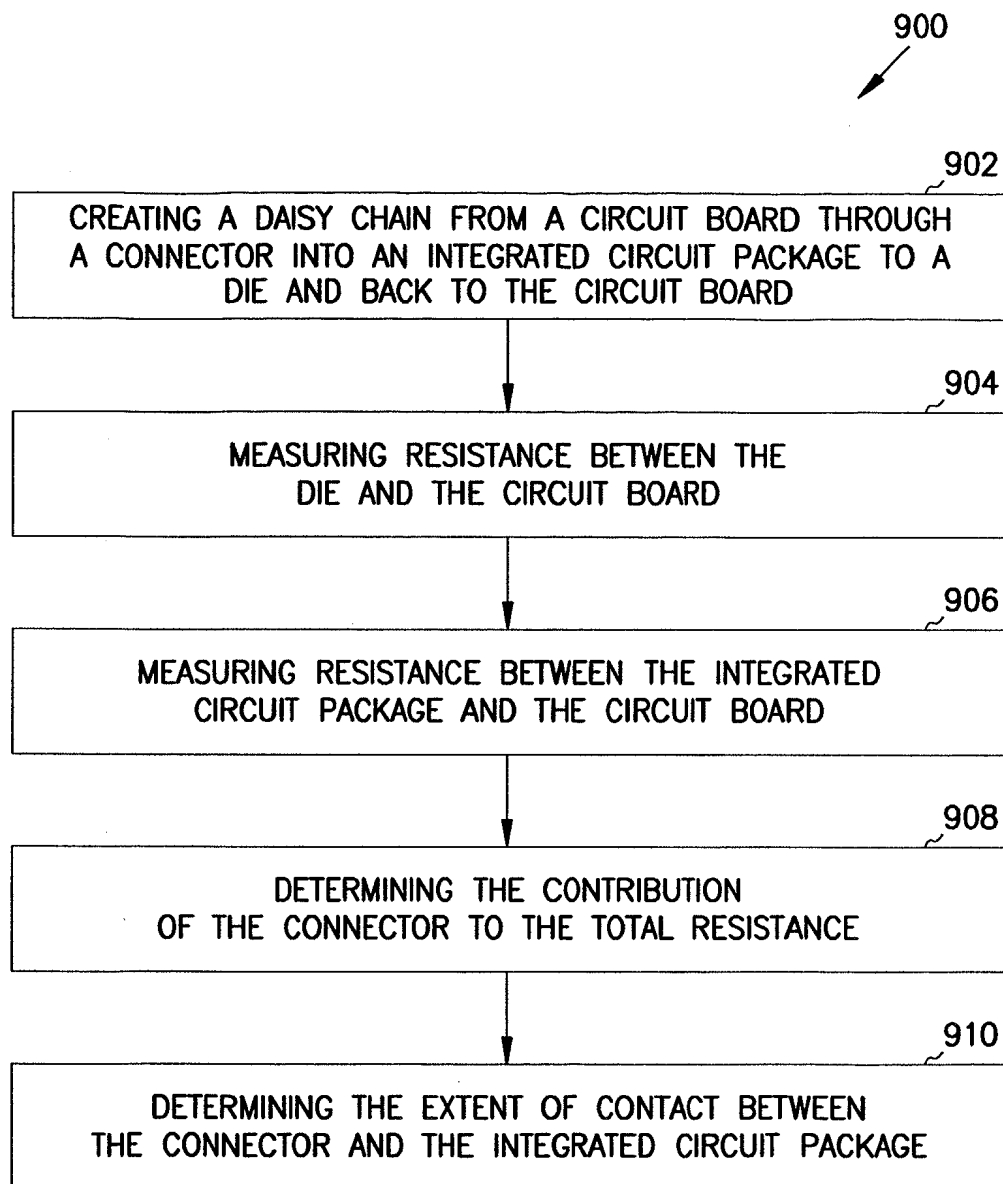


FIG. 9



1000

1002

PLACING AN INTEGRATED CIRCUIT  
PACKAGE ON THE CIRCUIT BOARD

1004

PLACING A SLIGHTLY CURVED PRESSURE PLATE  
ON A TOP SURFACE OF THE INTEGRATED CIRCUIT PACKAGE

1006

PLACING A GASKET BETWEEN THE INTEGRATED  
CIRCUIT PACKAGE AND THE SLIGHTLY CURVED PRESSURE PLATE

1008

PLACING A SLIGHTLY CURVED BACKING PLATE  
ON A BOTTOM SURFACE OF THE CIRCUIT BOARD

1010

APPLYING FORCE TO THE OUTER EDGES OF THE PLATES TO  
RETAIN THE INTEGRATED CIRCUIT PACKAGE ON THE CIRCUIT  
BOARD AND TO CREATE AN EVENLY DISTRIBUTED PRESSURE  
ACROSS CONDUCTORS OF THE INTEGRATED CIRCUIT PACKAGE

1012

PLACING A HEAT SINK ON THE  
SLIGHTLY CURVED PRESSURE PLATE

1014

ATTACHING THE HEAT SINK TO THE CIRCUIT BOARD

FIG. 10